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## Future Disruptions

S. Raithel  
COO  
DAS Environmental Expert GmbH, Dresden,  
Germany

**DAS**

Environmental Experts.

### Body

Session Chair

### Biography

Stephan Raithel joined DAS in 2016 and since then holds the position of the COO Gas Treatment. In his position he is overseeing all aspects of DAS' gas treatment products, such as development, engineering, product management, procurement, customer care and production.

From 2007 until 2016 he was working for SEMI, the global semiconductor equipment and materials association, where he held various positions within the association – from operations management, SEMI standards and PV Roadmap program to the role of the Managing Director of SEMI Europe.

Before his start in the semiconductor industry, he was employed as a project manager in the financial ,creative services and consumer goods industry.

References

## Sustainable by design: How Soitec drives the transition toward a sustainable economy through innovation and operations

F. Bernard  
Deputy Sustainability  
Soitec, Bernin, France

**soitec**

### Body

At Soitec, our products are designed and manufactured to provide greater performance, security and agility, while guaranteeing energy efficiency to the resulting applications. This is the heart of our technology and our value proposition. Sustainability thus integrates Soitec's core business with the energy efficiency of its products. This has naturally inspired and structured the way we conduct our activities.

For several years, we have been constantly innovating to manage our activities more sustainably, with a particular attention to reducing the carbon footprint of the entire microelectronics value chain, reducing our water withdrawals and taking into account environmental criteria in the design of our products.

### **Biography**

Fanny Bernard joined Soitec in 2010 and is currently Deputy of Sustainability Department. She works on issues of impact and responsibility, both on the environmental, societal and territorial aspects.

With more than 10 years of experience in corporate and internal communications in international industrial environments, Fanny specializes in ESG and benefits from expertise around responsibility and sustainability issues. From 2020, as ESG manager, she was responsible for creating and implementing Soitec's ESG strategy in line with the company's strategy. She has coordinated the different stakeholders, set up extra-financial reporting and worked to raise awareness and popularize all of the group's commitments to various audiences such as employees, investors, institutions and the general public.

Fanny graduated from Sciences Po Strasbourg and Grenoble Ecole de Management.

References

## **Co-Optimized Heterogeneous Augmented Reality Systems Enabled with Wearable and Personalized Artificial Intelligence**

S. Kang  
Senior Vice President of Semiconductor Strategy  
Adeia, Semiconductor Strategy, San Jose, United  
States of America

### **Body**

The proliferation of AI into new verticals will drive the co-integration of silicon devices, optical devices, and sensors into a unified platform. One can envision an AI-enabled augmented reality system that is always on, wearable, and personalized. This can serve as a flagship heterogeneous system co-optimized for computing, energy efficiency, and seamless user interface, while also prioritizing small form factor, comfort, and trendy design. From a semiconductor hardware perspective, a key enabler is the co-integration of an energy-efficient AI system built on silicon with an ultra-high-resolution III-V display device and state-of-the-art sensors. Such a system must function in all wearable environments, including bright sunlight and extreme weather conditions. Due to the heterogeneous nature and a tiny form factor requirement, this system necessitates an advanced three-dimensional integration. This presentation will provide an overview of such an emerging platform and its key technological attributes from the perspective of heterogeneous semiconductor integration and co-optimization.

### **Biography**

Dr. Seung Kang serves as Senior Vice President of Semiconductor Strategy at Adeia, where he oversees strategic semiconductor programs encompassing technology, design, and system co-optimization. Prior to joining Adeia, Dr. Kang held a distinguished career at Qualcomm Technologies, Inc., where he spearheaded the Advanced Memory Program, pioneering early R&D and IP validation across the semiconductor ecosystem. His leadership also extended to the development of foundational logic IP for semiconductor nodes ranging from 7 nanometers down to 3 nanometers, supporting Qualcomm's flagship mobile, automotive, AI, and IoT products. Before his tenure at Qualcomm, Dr. Kang made significant contributions at Lucent Technologies Bell Laboratories and Lawrence Berkeley National Laboratory. He earned his B.S. and M.S. degrees from Seoul National University, Korea, and a Ph.D. from the University of California, Berkeley. Dr. Kang is a highly accomplished inventor, holding 250 U.S. patents and over 1000 patents granted globally. His research contributions are widely recognized, with over 100 published papers. He served as a Distinguished Lecturer for the IEEE Electron Device Society from 2014 to 2018 and has been a Specially Appointed Visiting Professor at the Center for Innovative Integrated Electronic Systems, Tohoku University, Japan.

References

## **Jumping the Barriers of Future Lithography**

M. van de Kerkhof  
Director EUV Research  
ASML, Research, Helmond, Netherlands

### **Body**

In the past years, EUV lithography has been adopted for manufacturing of state-of-the-art Integrated Circuits, with critical dimensions down to 10 nm. With the introduction of a larger NA=0.55, these dimensions will become smaller still. This will further tighten requirements on CD and pattern placement control to ensure yielding devices with dimensions below 10 nm, raising questions on the limits of the shrink that may be achieved in manufacturing reality, in terms of both exposures and chemical and etching processes. At the same time, investigations have started to push these limits even further by increasing the NA even further to NA=0.75 or beyond, or alternatively to lower the wavelength below 13.5 nm.

This presentation will discuss the principles of EUV Lithography, its challenges and limitations for NA=0.33 and NA=0.55, and possible options to jump the barriers holding us back from doing lithography at critical dimensions down to 5 nm.

### **Biography**

Mark A. van de Kerkhof is the Director for EUV Projects at ASML Research, based in Veldhoven, The Netherlands.

He received an M.Sc. in Applied Physics from Eindhoven University of Technology, and a PhD in EUV-induced Plasma, also at Eindhoven University of Technology. He began his career at ODME, working on the development mastering processes for DVD and Blu-Ray. In 1999 he joined ASML as senior designer and later project manager, working on development of miscellaneous sensors as well as projection optics in both DUV and EUV scanners. He currently is Director for EUV projects at ASML Research, as well as assistant professor for Plasma Physics at Eindhoven University of Technology.

He holds over 100 patents and authored or co-authored more than 50 scientific papers. He frequently presents at conferences about both photolithography and plasma physics. He is a Fellow of SPIE.

References